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bq24298 EVM-655

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB	1		Printed Circuit Board		PWR655	Any	-	-
C1	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	C1608X7R1E105K080A B	TDK		
C2	1	10uF	CAP, CERM, 10uF, 25V, +/-10%, X5R, 0805	0805	C2012X5R1E106K125A B	TDK		
C3	1	4.7uF	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603	GRM188R61C475KAAJ	MuRata		
C4	1	0.047uF	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0402	0402	GRM155R71E473KA88 D	MuRata		
C5, C6, C7	3	10uF	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603	C1608X5R1A106M	TDK		
C21	1	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X7R, 0402	0402	GRM155R71A104KA01 D	MuRata		
C22	1	0	RES, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
D3, D4	2	Green	LED, Green, SMD	1.6x0.8x0.8mm	LTST-C190GKT	Lite-On		
H1, H2, H3, H4	4		Bumpon, Cylindrical, 0.312 X 0.200, Black	Black Bumpon	SJ61A1	3M		
J1, J2, J3, J4	4	2x1	Conn Term Block, 2POS, 3.81mm, TH	2POS Terminal Block	1727010	Phoenix Contact		
J5	1		Connector, Receptacle, Micro-USB Type B, R/A, Bottom Mount SMT	7.5x2.45x5mm	0473460001	Molex		
J6	1		Terminal Block, 6A, 3.5mm Pitch, 4-Pos, TH	14x8.2x6.5mm	ED555/4DS	On-Shore Technology		
J7	1		Header (shrouded), 100mil, 5x2, High-Temperature, Gold, TH	5x2 Shrouded header	N2510-6002-RB	3M		
J8, J9, JP5, JP6, JP7, JP8, JP9, JP10, JP11	9		Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions		
JP1, JP2, JP3, JP4	4		Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions		
L1	1	1uH	Inductor, Flat Wire, Powdered Iron, 1uH, 4.8A, 0.0336 ohm, SMD	4.7x1.2x4.0mm	SRP4012-1R0M	Boums		
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady	-	-
R1	1	130	RES, 130 ohm, 1%, 0.063W, 0402	0402	CRCW0402130RFKED	Vishay-Dale		
R2	1	5.23k	RES, 5.23k ohm, 1%, 0.063W, 0402	0402	CRCW04025K23FKED	Vishay-Dale		
R3	1	30.1k	RES, 30.1k ohm, 1%, 0.063W, 0402	0402	CRCW040230K1FKED	Vishay-Dale		
R4, R5, R7, R14, R15, R23	6	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R8, R9, R10, R11, R12	5	200	RES, 200 ohm, 1%, 0.063W, 0402	0402	CRCW0402200RFKED	Vishay-Dale		
R13	1	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
R16	1	150k	RES, 150k ohm, 1%, 0.063W, 0402	0402	CRCW0402150KFKED	Vishay-Dale		
R17	1	75.0k	RES, 75.0k ohm, 1%, 0.063W, 0402	0402	CRCW040275K0FKED	Vishay-Dale		
R18	1	768	RES, 768 ohm, 1%, 0.063W, 0402	0402	CRCW0402768RFKED	Vishay-Dale		
R19	1	50k	Trimmer, 50k, 0.25W, SMT	4.8x5.3x3.5mm	3214W-1-503E	Boums		
R21, R22	2	2.21k	RES, 2.21k ohm, 1%, 0.063W, 0402	0402	CRCW04022K21FKED	Vishay-Dale		
S1	1		Switch, Normally open, 2.3N force, 200k operations, SMD	KSR	KSR221GLFS	C and K Components		

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
SH-JP1, SH-JP2, SH-JP3, SH-JP8, SH-JP9, SH-JP10	6	1x2	Shunt, 100mil, Gold plated, Black	Shunt	969102-0000-DA	3M	SNT-100-BK-G	Samtec
TP1	1		Compact Probe Tip Circuit Board Test Points, TH, 25 per	TH Scope Probe	131-5031-00	Tektronix		
TP2, TP3	2	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone		
TP4, TP11	2	Orange	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint	5003	Keystone		
TP5	1	Yellow	Test Point, Miniature, Yellow, TH	Yellow Miniature Testpoint	5004	Keystone		
TP6, TP7, TP8	3	SMT	Test Point, Compact, SMT	Testpoint_Keystone_Compact	5016	Keystone		
TP9, TP10, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20	11	White	Test Point, Miniature, White, TH	White Miniature Testpoint	5002	Keystone		
U1	1		I2C Controlled 3A Single Cell USB Charger With Narrow VDC Power Path Management and Adjustable Voltage USB OTG, RTW0024H	RTW0024H	BQ24298RTWR	Texas Instruments	BQ24298RTWT	Texas Instruments
C8, C10, C17, C20	0	1000pF	CAP, CERM, 1000pF, 25V, +/-5%, C0G/NP0, 0402	0402	C1005C0G1E102J	TDK		
C9	0	2.2uF	CAP, CERM, 2.2uF, 25V, +/-10%, X5R, 0402	0402	C1005X5R1E225K050B C	TDK		
C11, C12, C13	0	10uF	CAP, CERM, 10uF, 25V, +/-20%, X5R, 0603	0603	GRM188R61E106MA73	MuRata		
C14	0	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A104KA01 D	MuRata		
C15, C16, C19	0	10uF	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603	C1608X5R1A106M	TDK		
C18	0	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A105KE15 D	MuRata		
D1, D5	0	40V	Diode, Schottky, 40V, 0.38A, SOD-523	SOD-523	ZLLS350TA	Diodes Inc.		
D2	0	20V	Diode, Schottky, 20V, 1A, 1.4x0.6x0.31mm	1.4x0.6x0.31mm	NSR10F20NXT5G	ON Semiconductor		
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A		
R6, R26	0	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R20	0	100k	RES, 100k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale		
R24	0	5.23k	RES, 5.23k ohm, 1%, 0.063W, 0402	0402	CRCW04025K23FKED	Vishay-Dale		
R25	0	30.1k	RES, 30.1k ohm, 1%, 0.063W, 0402	0402	CRCW040230K1FKED	Vishay-Dale		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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